

Simulations of the effect of interface traps distribution on the electrical parameters of normally-off AlGaN/GaN MOS-HEMTs

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Introduction

High Electron Mobility Transistors based on the AIGaN/GaN heterostructures can be used for power electronics owing to the excellent electro-physical properties of III-N materials, such as high critical electric field and high carrier concentration and mobility of two-dimensional electron gas (2DEG) in the channel. One of the essential requirements is enhancement mode (normally-off) operation. Several different layouts have been developed to fulfil the principal assumption and one of the most promising are the recessed gate design or a hybrid MOS-HEMT structure. However, the major drawback of the latter structure is poor quality of GaN/dielectric interface which may cause low mobility and high on-resistance of final devices. The aim of this work is to investigate how various interface traps distribution profiles affect electrical characteristics and parameters of normally-off AlGaN/GaN HEMTs.

Simulation details

